

# MU10N280L

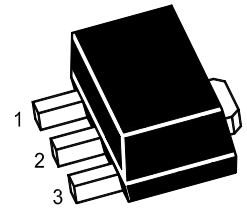
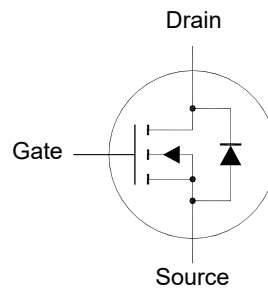
## N-Channel Enhancement Mode MOSFET

### Features

- Low Leakage Current

### Applications

- Portable appliances
- Battery management



1.Gate 2.Drain 3.Source  
SOT-89 Plastic Package

### Absolute Maximum Ratings (at $T_a = 25^\circ\text{C}$ unless otherwise specified)

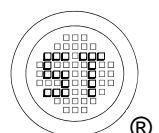
Parameter	Symbol	Value	Unit
Drain Source Voltage	$V_{DS}$	100	V
Gate Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current	$I_D$	1.5	A
Peak Drain Current, Pulsed <sup>1)</sup>	$I_{DM}$	8	A
Power Dissipation <sup>2)</sup>	$P_D$	1.5	W
Operating Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	- 55 to + 150	$^\circ\text{C}$

### Thermal Resistance Ratings

Parameter	Symbol	Max.	Unit
Thermal Resistance from Junction to Ambient <sup>2)</sup>	$R_{\theta JA}$	83.3	$^\circ\text{C/W}$

<sup>1)</sup> Pulse Test: Pulse Width  $\leq 100 \mu\text{s}$ , Duty Cycle  $\leq 2\%$ , Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})} = 150^\circ\text{C}$ .

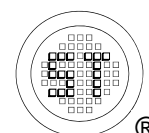
<sup>2)</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air.



# MU10N280L

Characteristics at  $T_a = 25^\circ\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit
<b>STATIC PARAMETERS</b>					
Drain-Source Breakdown Voltage at $I_D = 250 \mu\text{A}$	$V_{(BR)DSS}$	100	-	-	V
Zero Gate Voltage Drain Current at $V_{DS} = 80 \text{ V}$	$I_{DSS}$	-	-	1	$\mu\text{A}$
Gate-Source Leakage at $V_{GS} = \pm 20 \text{ V}$	$I_{GSS}$	-	-	$\pm 100$	nA
Gate-Source Threshold Voltage at $V_{GS} = V_{DS}, I_D = 250 \mu\text{A}$	$V_{GS(th)}$	1	-	2.5	V
Drain-Source On-State Resistance at $V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}$ at $V_{GS} = 4.5 \text{ V}, I_D = 1 \text{ A}$	$R_{DS(on)}$	- -	- -	280 310	m $\Omega$
<b>DYNAMIC PARAMETERS</b>					
Forward Transconductance at $V_{DS} = 5 \text{ V}, I_D = 1 \text{ A}$	$g_{Fs}$	-	3.5	-	S
Gate resistance at $V_{DS} = 0 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	$R_g$	-	1	-	$\Omega$
Input Capacitance at $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	$C_{iss}$	-	466	-	pF
Output Capacitance at $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	$C_{oss}$	-	17.5	-	pF
Reverse Transfer Capacitance at $V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	$C_{rss}$	-	13.5	-	pF
Total Gate Charge at $V_{DS} = 50 \text{ V}, I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}$ at $V_{DS} = 50 \text{ V}, I_D = 2 \text{ A}, V_{GS} = 4.5 \text{ V}$	$Q_g$	- -	8.6 4	- -	nC
Gate-Source Charge at $V_{DS} = 50 \text{ V}, I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}$	$Q_{gs}$	-	1.8	-	nC
Gate-Drain Charge at $V_{DS} = 50 \text{ V}, I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}$	$Q_{gd}$	-	1	-	nC
Turn-On Delay Time at $V_{DS} = 50 \text{ V}, I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}, R_G = 6 \Omega$	$t_{d(on)}$	-	9.5	-	ns
Turn-On Rise Time at $V_{DS} = 50 \text{ V}, I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}, R_G = 6 \Omega$	$t_r$	-	3.1	-	ns
Turn-Off Delay Time at $V_{DS} = 50 \text{ V}, I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}, R_G = 6 \Omega$	$t_{d(off)}$	-	8.4	-	ns
Turn-Off Fall Time at $V_{DS} = 50 \text{ V}, I_D = 2 \text{ A}, V_{GS} = 10 \text{ V}, R_G = 6 \Omega$	$t_f$	-	12.7	-	ns
<b>Body-Diode PARAMETERS</b>					
Drain-Source Diode Forward Voltage at $V_{GS} = 0 \text{ V}, I_S = 1 \text{ A}$	$V_{SD}$	-	-	1.2	V
Body-Diode Continuous Current	$I_S$	-	-	1.5	A
Body Diode Reverse Recovery Time at $I_S = 2 \text{ A}, di/dt = 100 \text{ A} / \mu\text{s}$	$t_{rr}$	-	16	-	ns
Body Diode Reverse Recovery Charge at $I_S = 2 \text{ A}, di/dt = 100 \text{ A} / \mu\text{s}$	$Q_{rr}$	-	12.8	-	nC



## Electrical Characteristics Curves

Fig. 1 Typical Output Characteristics

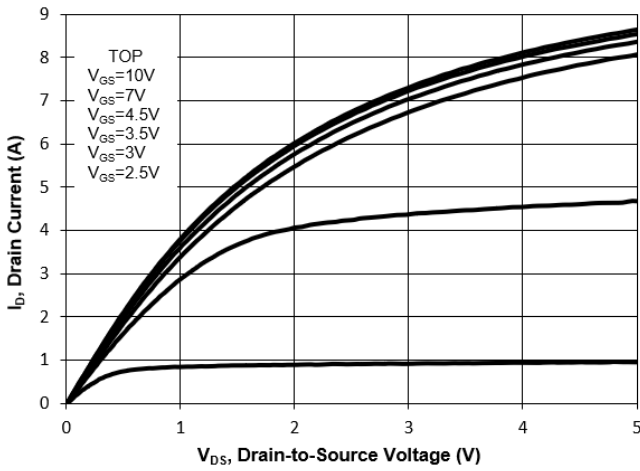


Fig. 2 Typical Transfer Characteristics

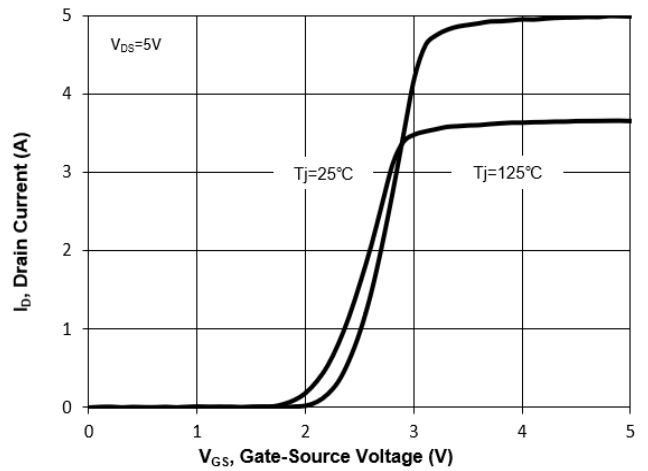


Fig. 3 on-Resistance vs. Drain Current

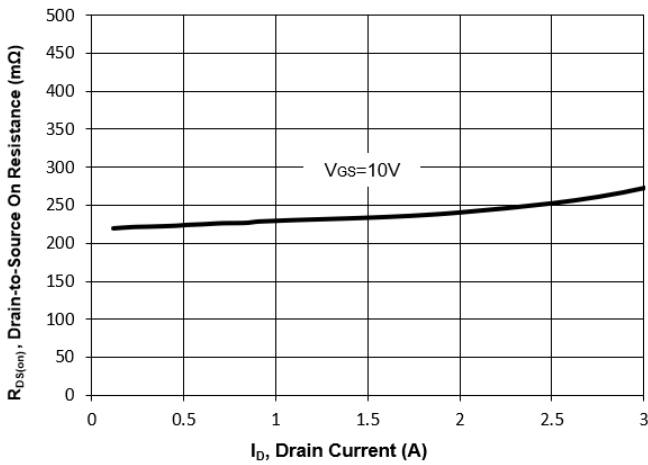


Fig. 4 On-Resistance vs. Gate-Source Voltage

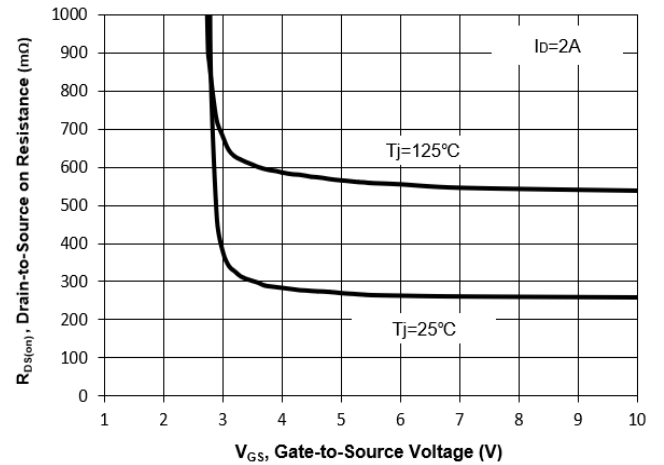


Fig. 5 on-Resistance vs. Tj

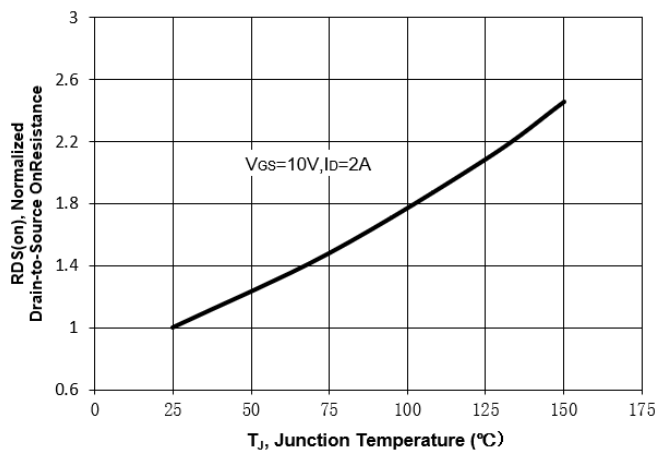
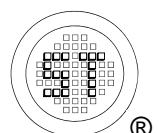
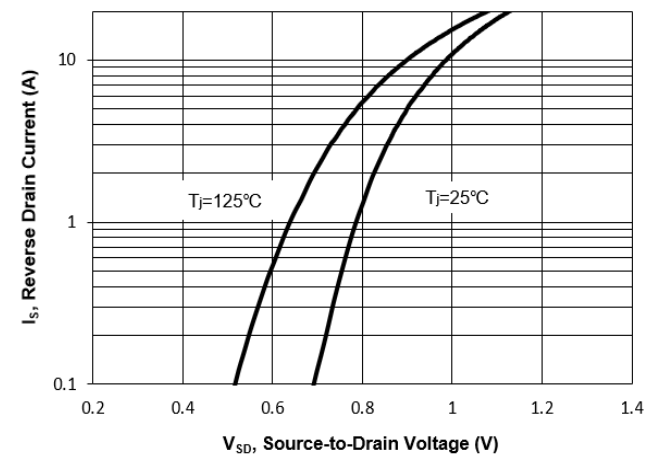


Fig. 6 Typical Forward Characteristics



## Electrical Characteristics Curves

Fig. 7 Typical Junction Capacitance

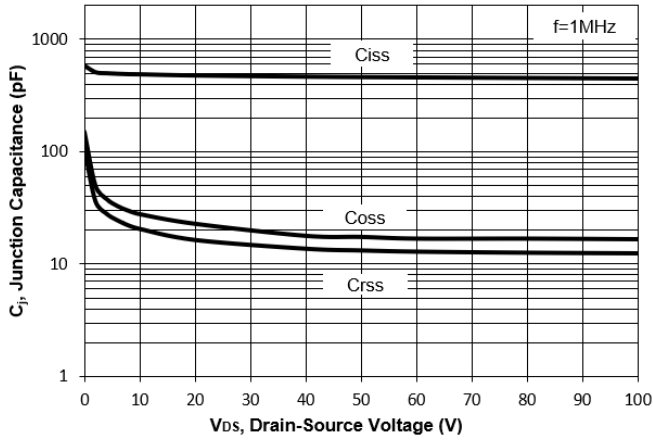


Fig. 8 Drain-Source Leakage Current vs.  $T_J$

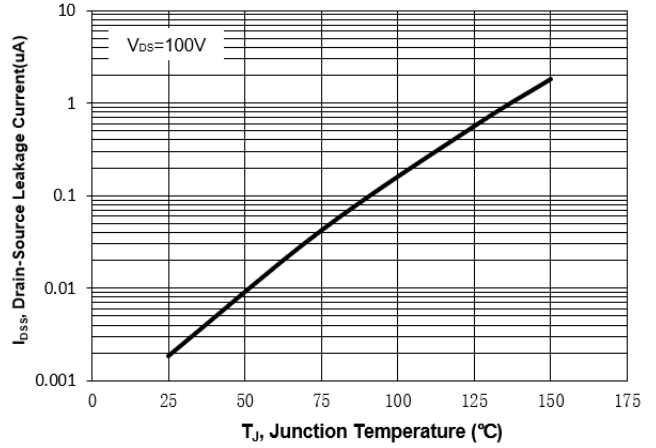


Fig. 9  $V_{(BR)DSS}$  vs. Junction Temperature

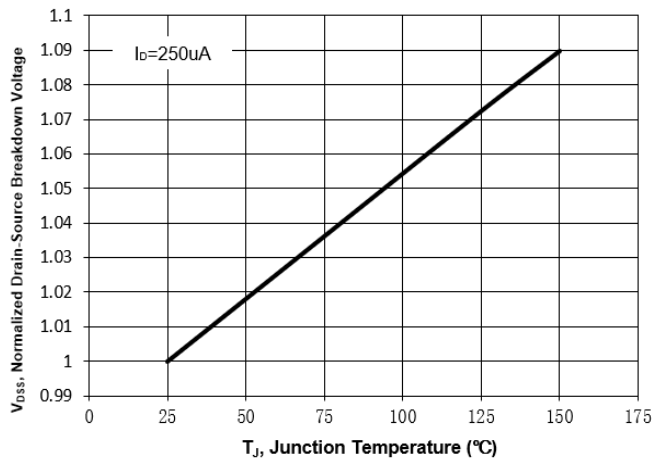


Fig. 10 Gate Threshold Variation vs.  $T_J$

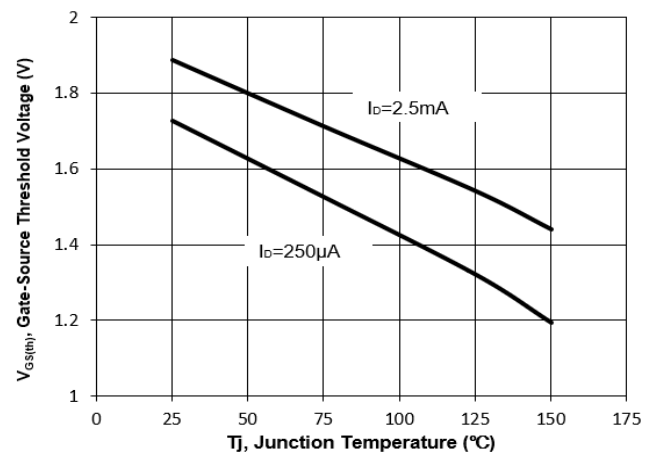
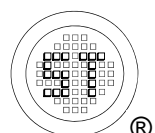
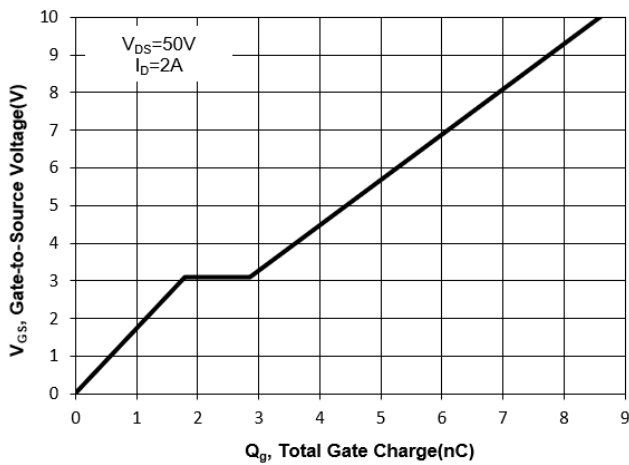


Fig. 11 Gate Charge



## Test Circuits

Fig.1-1 Switching times test circuit

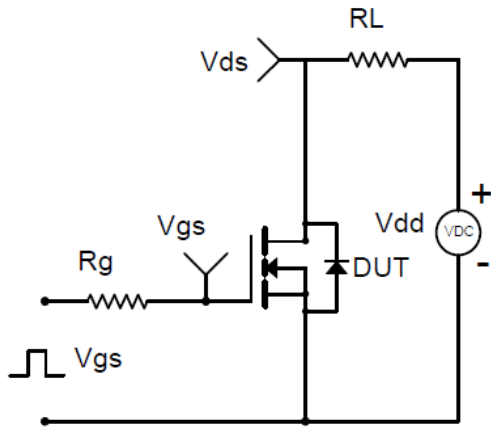


Fig.1-2 Switching Waveform

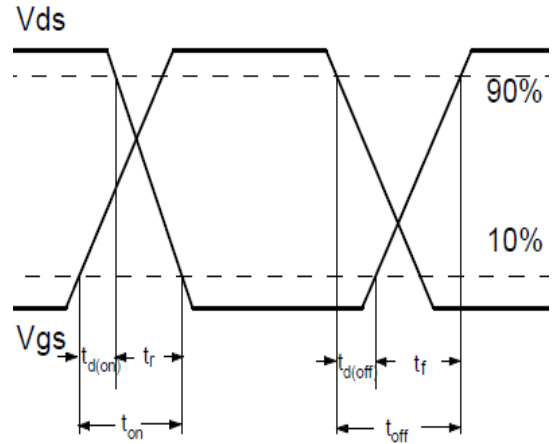


Fig.2-1 Gate charge test circuit

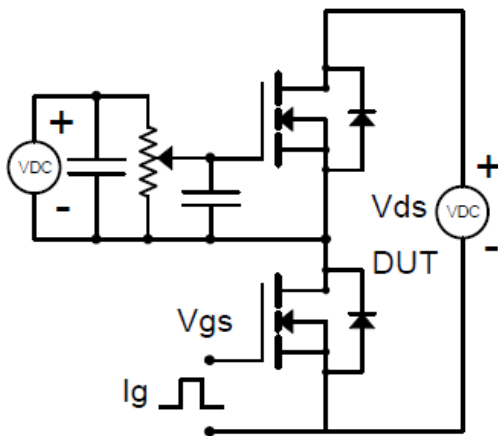
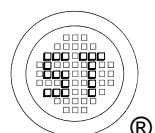
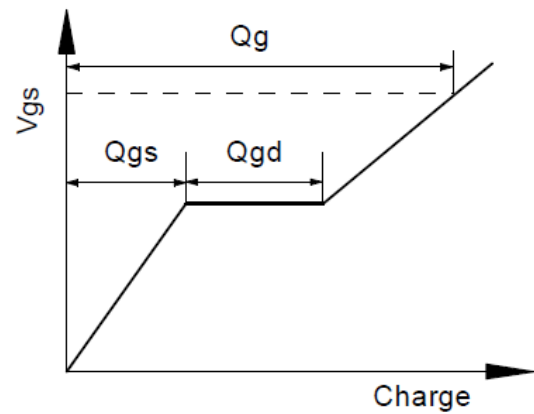


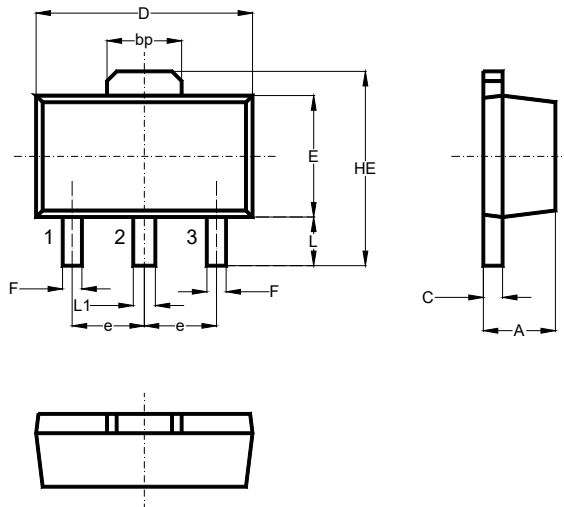
Fig.2-2 Gate charge waveform



# MU10N280L

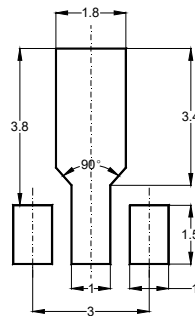
## Package Outline (Dimensions in mm)

SOT-89



Unit	A	bp	C	D	E	F	HE	e	L	L1
mm	1.6	1.60	0.5	4.6	2.6	0.45	4.25	1.5	1.05	0.51
	1.4	1.50	0.3	4.4	2.4	0.35	3.75	typ.	0.95	0.41

## Recommended Soldering Footprint



## Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
SOT-89	12	8 ± 0.1	0.315 ± 0.004	178	7	1,000
				330	13	4,000

## Marking information

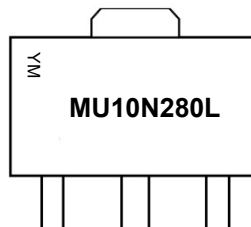
" MU10N280L " = Part No.

" YM " = Date Code Marking

" Y " = Year

" M " = Month

Font type: Arial



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